



Material Content Data Sheet



Sales Product Name		SPD04P10PL G		Issued		25. September 2017		
MA#		MA000443074						
Package		PG-TO252-3-311		Weight*		312.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.091	0.35	0.35	3488	3488
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		458	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	copper	7440-50-8	143.098	45.72	45.78	457316	457911
wire	non noble metal	aluminium	7429-90-5	0.585	0.19	0.19	1871	1871
encapsulation	inorganic material	antimonytrioxide	1309-64-4	2.011	0.64		6428	
	plastics	brominated resin	-	2.155	0.69		6887	
	organic material	carbon black	1333-86-4	2.299	0.73		7346	
	plastics	epoxy resin	-	19.396	6.20		61986	
	inorganic material	silicondioxide	60676-86-0	117.811	37.65	45.91	376505	459152
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11953	11953
plating	non noble metal	nickel	7440-02-0	0.086	0.03		276	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	277
solder	noble metal	silver	7440-22-4	0.031	0.01		100	
	non noble metal	tin	7440-31-5	0.025	0.01		80	
	non noble metal	lead	7439-92-1	1.189	0.38	0.40	3801	3981
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61288	61367
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com